

## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	<b>METHOD FOR FABRICATING SEMICONDUCTOR PACKAGES, AND LEADFRAME ASSEMBLIES FOR THE FABRICATION THEREOF</b>		
Application Type: regular, utility			
Attorney Docket Number: 27-021			
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

**Publication Information:**

Suggested Figure for Publication – FIG. 8

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